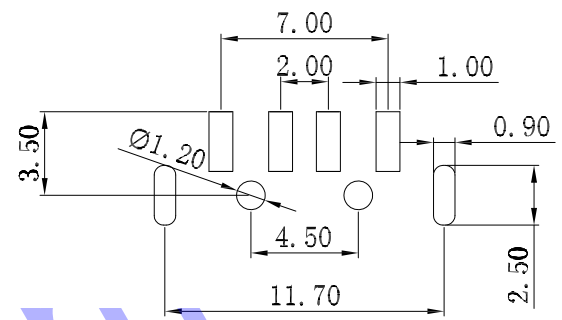
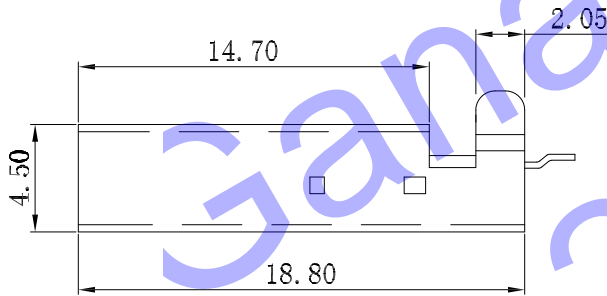
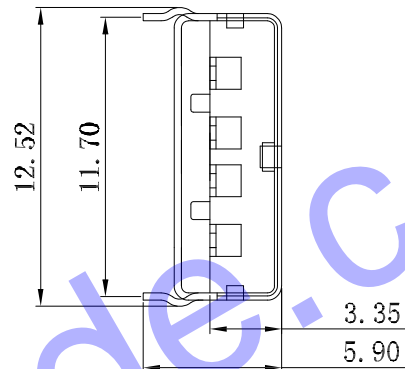
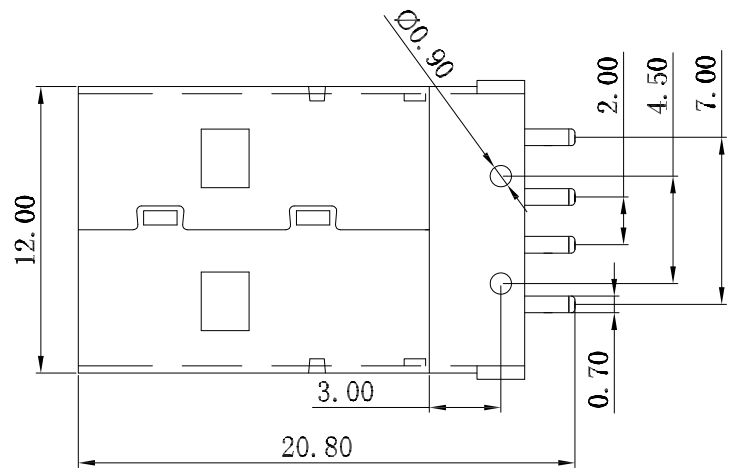


HS

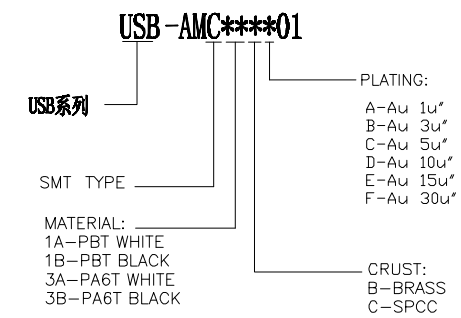


PCB LAYOUT

NOTE:

- 1.MATERIAL:
 - a.HOUSING:THERMOPLASTIC GLASS FIBRE
 - b.CONTACT:BRASS T=0.20mm
(SURFACE PLATING: Au* μ " + Sn100 μ " + Ni50 μ " Min) SEE ORDERING INFORMATION
 - c.CRUST: T=0.30mm
(SURFACE PLATING: Ni80 μ " ~ 100 μ ") SEE ORDERING INFORMATION
- 2.ELECTRIC:
 - a.CONTACT RESISTANCE: 30 MILLIOHMS MAX
 - b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN
 - c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL
 - d.OPERATING TEMPERATURE: -55° C ~ +85° C

ORDERING INFORMATION



REV	DESCRIPTION	DATE	QUALITY SYMBOLS ■ : CRITICAL ▽ : ZERO DEFECT ☒ : MAJOR ▽ : S.P.C	UNIT mm	SCALE 2.5 : 1	TOLERANCES DIM. ± 0.20 ANGLE: 3°	ITEM	DESC	Q'TY	MATERIAL	REMARKS	PART REMARKS
							APPROVED	CHECKED	DESIGN	DRAWN	PART NO.	USB-AMCXXX01
B	应客户要求, 更改结构	'16-07-09										
A	图面发行	'09-12-09										

H D C 有限公司

DESCRIPTION: USB AM 180度 SMT
DRAWING NO.:
REV: B